

Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Texas Instruments](#)

[ULN2004AIDR](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

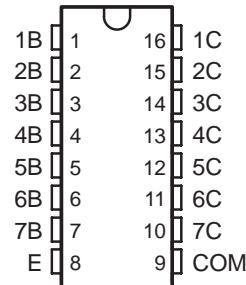
- **500-mA-Rated Collector Current (Single Output)**
- **High-Voltage Outputs . . . 50 V**
- **Output Clamp Diodes**
- **Inputs Compatible With Various Types of Logic**
- **Relay-Driver Applications**

description/ordering information

The ULN2004AI is a high-voltage, high-current Darlington transistor array. This device consists of seven npn Darlington pairs that feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of a single Darlington pair is 500 mA. The Darlington pairs can be paralleled for higher-current capability. Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers.

The ULN2004AI has a 10.5-k Ω series base resistor for each Darlington pair for operation directly with TTL or 5-V CMOS devices.

**D, N, OR NS PACKAGE
(TOP VIEW)**



ORDERING INFORMATION

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	PDIP (N)	Tube of 25	ULN2004AIN	ULN2004AIN
	SOIC (D)	Tube of 40	ULN2004AID	ULN2004AI
		Reel of 2500	ULN2004AIDR	
	SOP (NS)	Reel of 2000	ULN2004AINSR	ULN2004AI

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

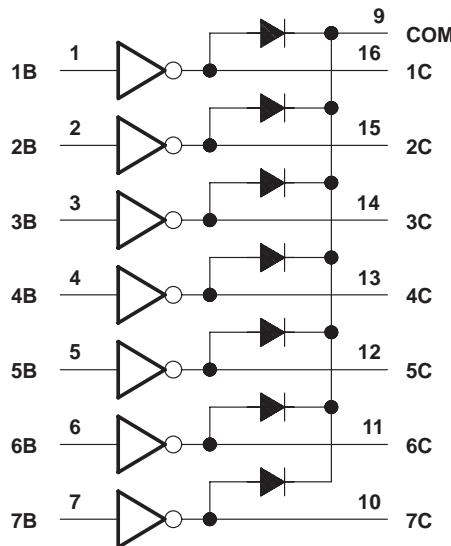


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

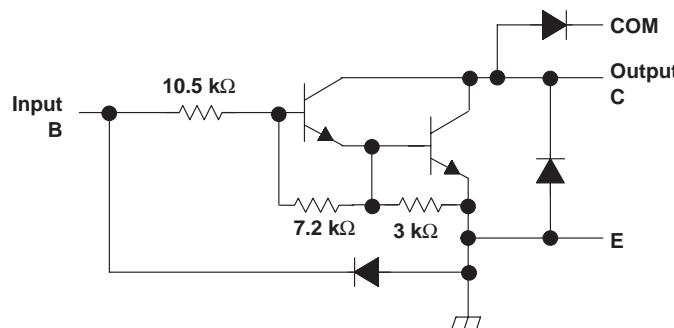
ULN2004AI
HIGH-VOLTAGE HIGH-CURRENT DARLINGTON
TRANSISTOR ARRAY

SLRS055 – APRIL 2004

logic diagram



schematics (each Darlington pair)



All resistor values shown are nominal.

absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)†

Collector-emitter voltage	50 V
Clamp diode reverse voltage (see Note 1)	50 V
Input voltage, V_I (see Note 1)	30 V
Peak collector current (see Notes 2 and 4)	500 mA
Output clamp current, I_{OK}	500 mA
Total emitter-terminal current	-2.5 A
Operating free-air temperature range, T_A	-40°C to 105°C
Package thermal impedance, θ_{JA} (see Notes 2 and 3):	D package	73°C/W
	N package	67°C/W
	NS package	64°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the emitter/substrate terminal E, unless otherwise noted.

2. Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST FIGURE	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{I(on)}$ On-state input voltage	6	$V_{CE} = 2\text{ V}$	$I_C = 125\text{ mA}$		5	V
			$I_C = 200\text{ mA}$		6	
			$I_C = 275\text{ mA}$		7	
			$I_C = 350\text{ mA}$		8	
$V_{CE(sat)}$ Collector-emitter saturation voltage	5	$I_I = 250\text{ }\mu\text{A},$ $I_C = 100\text{ mA}$		0.9	1.1	V
		$I_I = 350\text{ }\mu\text{A},$ $I_C = 200\text{ mA}$		1	1.3	
		$I_I = 500\text{ }\mu\text{A},$ $I_C = 350\text{ mA}$		1.2	1.6	
I_{CEX} Collector cutoff current	1	$V_{CE} = 50\text{ V},$ $I_I = 0$		50		μA
V_F Clamp forward voltage	8	$I_F = 350\text{ mA}$		1.7	2	V
I_I Input current	4	$V_I = 5\text{ V}$		0.35	0.5	mA
		$V_I = 12\text{ V}$		1	1.45	
I_R Clamp reverse current	7	$V_R = 50\text{ V}$		50		μA
C_i Input capacitance		$V_I = 0,$ $f = 1\text{ MHz}$	15	25		pF

ULN2004AI
HIGH-VOLTAGE HIGH-CURRENT DARLINGTON
TRANSISTOR ARRAY

SLRS055 – APRIL 2004

electrical characteristics, $T_A = -40^\circ\text{C}$ to 105°C

PARAMETER	TEST FIGURE	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{I(\text{on})}$ On-state input voltage	6	$V_{CE} = 2\text{ V}$	$I_C = 125\text{ mA}$		5	V
			$I_C = 200\text{ mA}$		6	
			$I_C = 275\text{ mA}$		7	
			$I_C = 350\text{ mA}$		8	
$V_{CE(\text{sat})}$ Collector-emitter saturation voltage	5	$I_I = 250\text{ }\mu\text{A},$ $I_I = 350\text{ }\mu\text{A},$ $I_I = 500\text{ }\mu\text{A},$	$I_C = 100\text{ mA}$	0.9	1.1	V
		$I_C = 200\text{ mA}$	1	1.3		
		$I_C = 350\text{ mA}$	1.2	1.6		
I_{CEX} Collector cutoff current	1	$V_{CE} = 50\text{ V},$	$I_I = 0$		50	μA
		$V_{CE} = 50\text{ V}$	$I_I = 0$		100	
	2		$V_I = 1\text{ V}$		500	
V_F Clamp forward voltage	8	$I_F = 350\text{ mA}$		1.7	2	V
$I_{I(\text{off})}$ Off-state input current	3	$V_{CE} = 50\text{ V},$	$I_C = 500\text{ }\mu\text{A}$	50	65	μA
I_I Input current	4	$V_I = 5\text{ V}$		0.35	0.5	mA
		$V_I = 12\text{ V}$		1	1.45	
I_R Clamp reverse current	7	$V_R = 50\text{ V}$			100	μA
C_i Input capacitance		$V_I = 0,$	$f = 1\text{ MHz}$		15	pF

switching characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} Propagation delay time, low- to high-level output	See Figure 8	0.25	1		μs
t_{PHL} Propagation delay time, high- to low-level output	See Figure 8	0.25	1		μs
V_{OH} High-level output voltage after switching	$V_S = 50\text{ V},$ See Figure 9	$I_O \approx 300\text{ mA},$ $V_S - 20$			mV

switching characteristics, $T_A = -40^\circ\text{C}$ to 105°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} Propagation delay time, low- to high-level output	See Figure 8	1	10		μs
t_{PHL} Propagation delay time, high- to low-level output	See Figure 8	1	10		μs
V_{OH} High-level output voltage after switching	$V_S = 50\text{ V},$ See Figure 9	$I_O \approx 300\text{ mA},$ $V_S - 500$			mV

PARAMETER MEASUREMENT INFORMATION

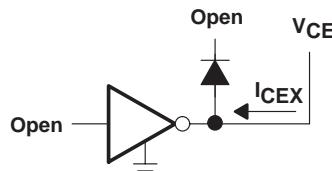


Figure 1. I_{CEx} Test Circuit

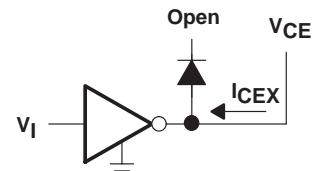


Figure 2. I_{CEx} Test Circuit

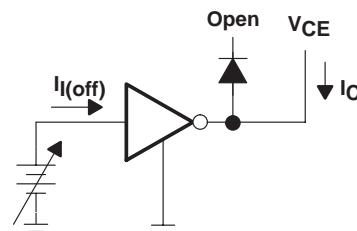


Figure 3. $I_{I(off)}$ Test Circuit

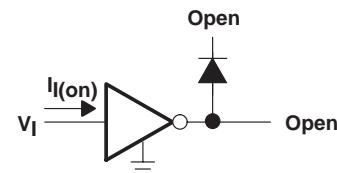
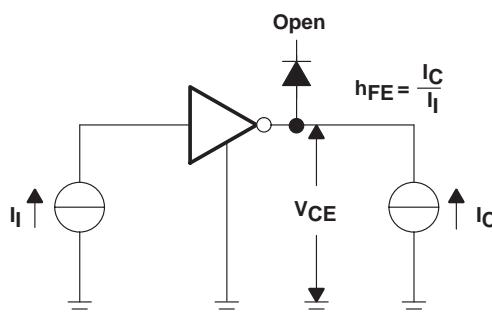


Figure 4. I_I Test Circuit



NOTE: I_I is fixed for measuring $V_{CE(sat)}$, variable for measuring hFE .

Figure 5. hFE , $V_{CE(sat)}$ Test Circuit

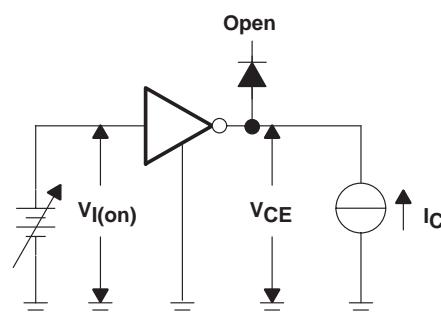


Figure 6. $V_{I(on)}$ Test Circuit

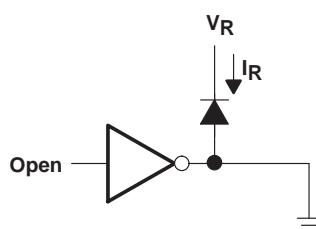


Figure 7. I_R Test Circuit

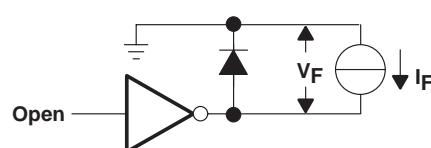


Figure 8. V_F Test Circuit

ULN2004AI
HIGH-VOLTAGE HIGH-CURRENT DARLINGTON
TRANSISTOR ARRAY
SLRS055 – APRIL 2004

PARAMETER MEASUREMENT INFORMATION

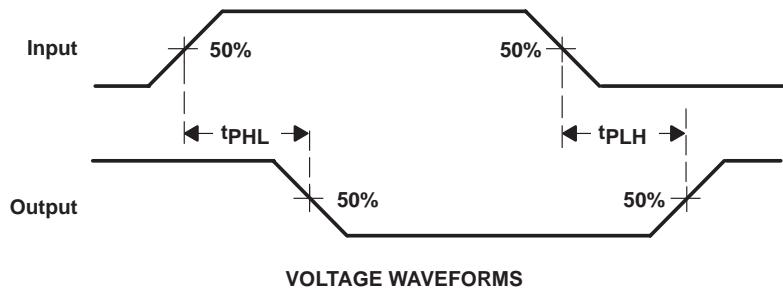
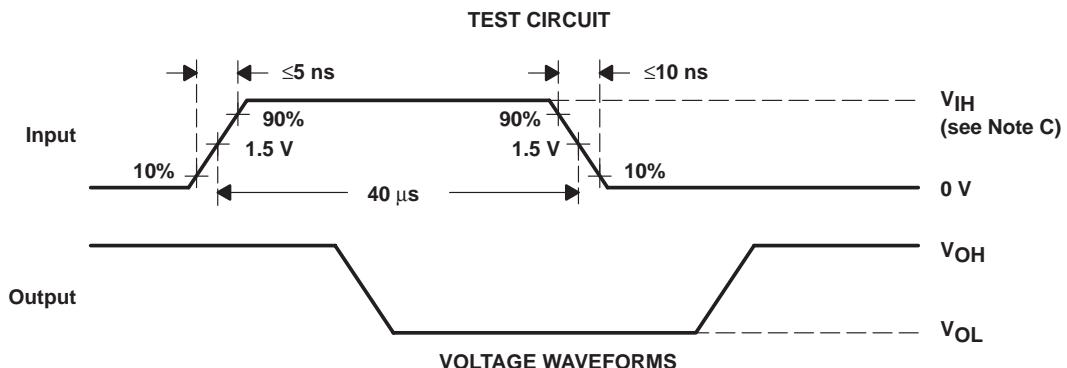
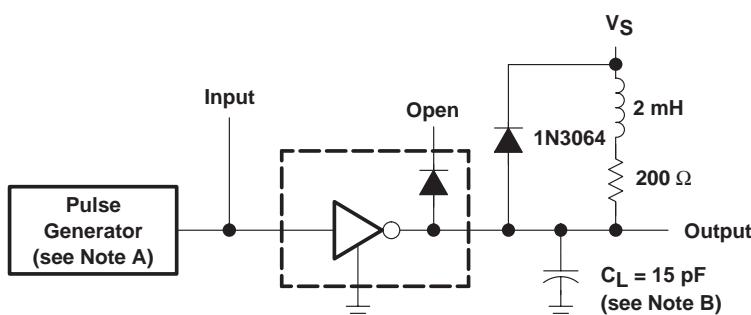


Figure 9. Propagation Delay-Time Waveforms



- NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz, $Z_O = 50 \Omega$.
 B. C_L includes probe and jig capacitance.
 C. For testing, $V_{IH} = 3 V$

Figure 10. Latch-Up Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

**COLLECTOR-EMITTER
SATURATION VOLTAGE
vs
COLLECTOR CURRENT
(ONE DARLINGTON)**

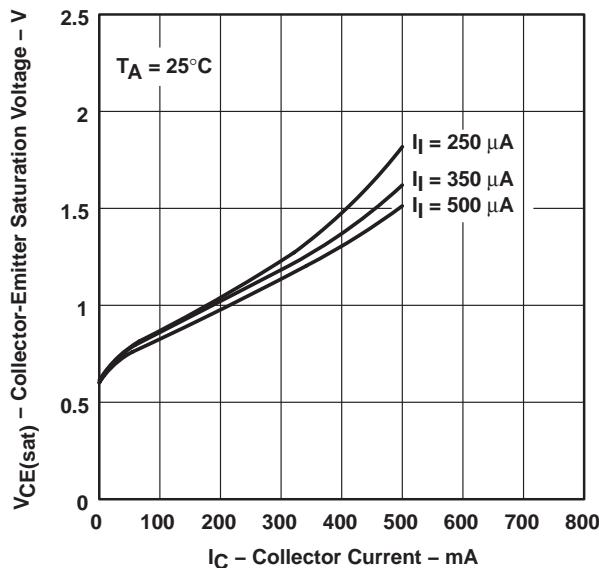


Figure 11

**COLLECTOR-EMITTER
SATURATION VOLTAGE
vs
TOTAL COLLECTOR CURRENT
(TWO DARLINGTONS IN PARALLEL)**

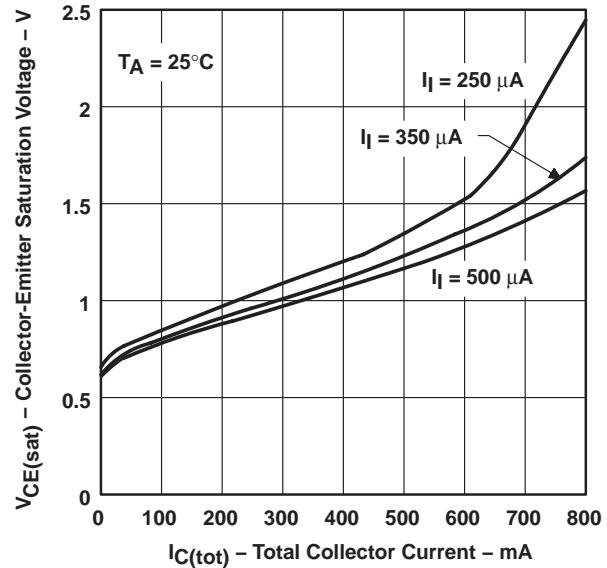


Figure 12

**COLLECTOR CURRENT
vs
INPUT CURRENT**

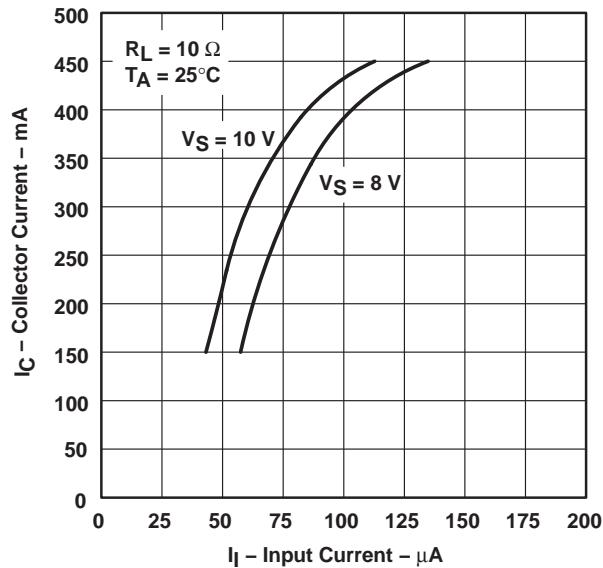


Figure 13

ULN2004AI
HIGH-VOLTAGE HIGH-CURRENT DARLINGTON
TRANSISTOR ARRAY
SLRS055 – APRIL 2004

APPLICATION INFORMATION

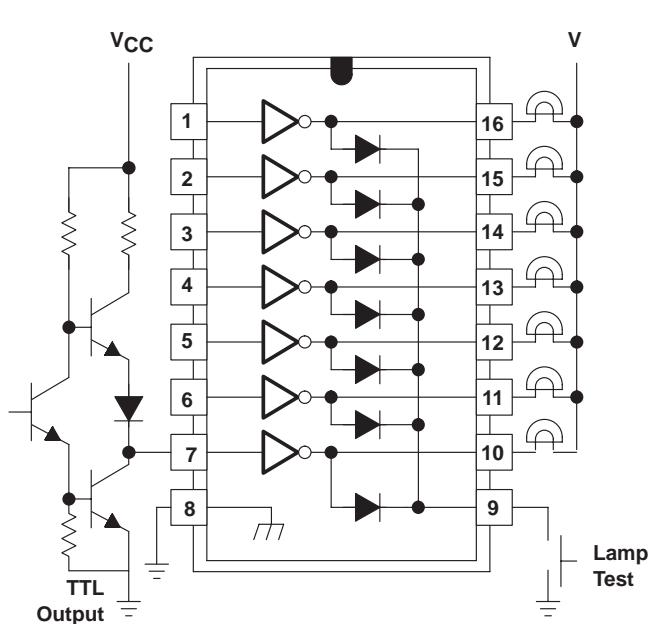


Figure 14. TTL to Load

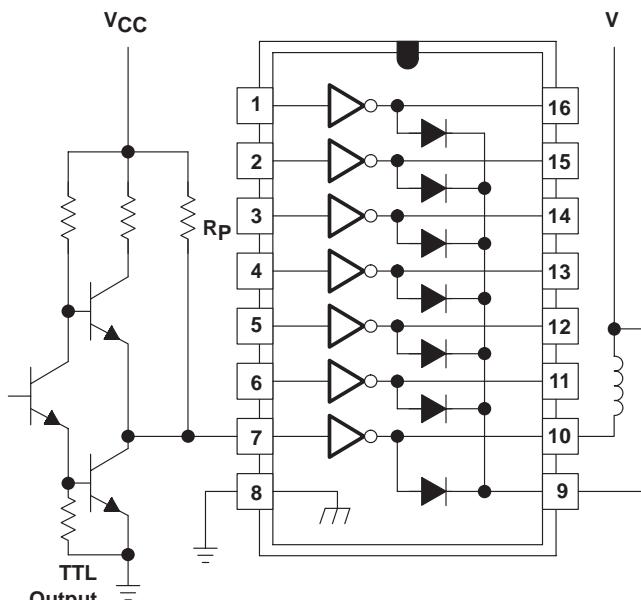


Figure 15. Use of Pullup Resistors
to Increase Drive Current

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ULN2004AID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	ULN2004AI	Samples
ULN2004AIDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	ULN2004AI	Samples
ULN2004AIDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	ULN2004AI	Samples
ULN2004AIN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 105	ULN2004AIN	Samples
ULN2004AINSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	ULN2004AI	Samples
ULN2004AINSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	ULN2004AI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

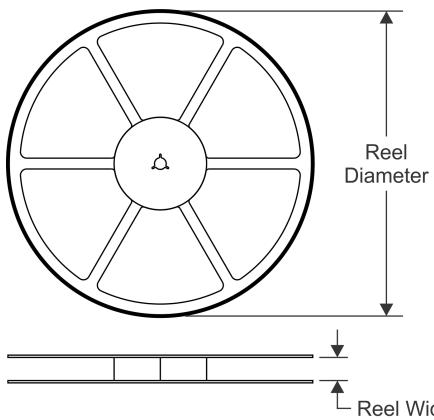
⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

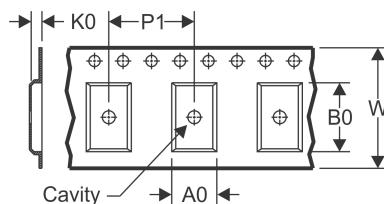
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

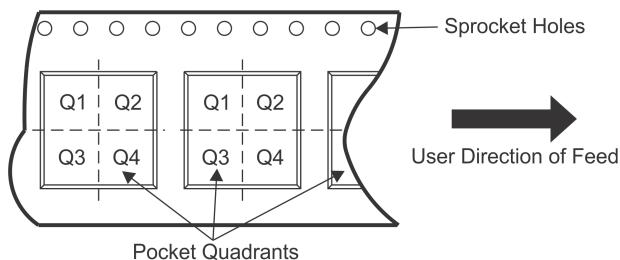


TAPE DIMENSIONS



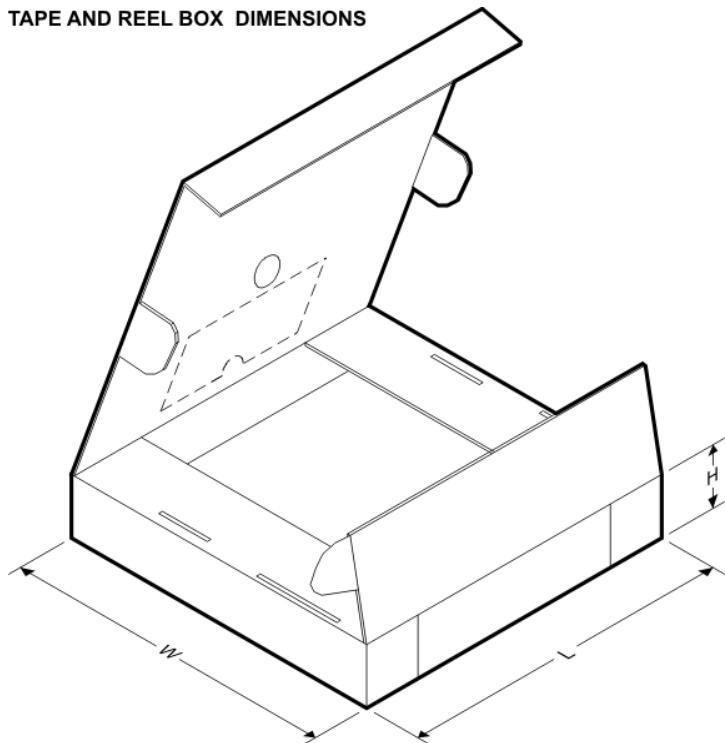
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ULN2004AIDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
ULN2004AINSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

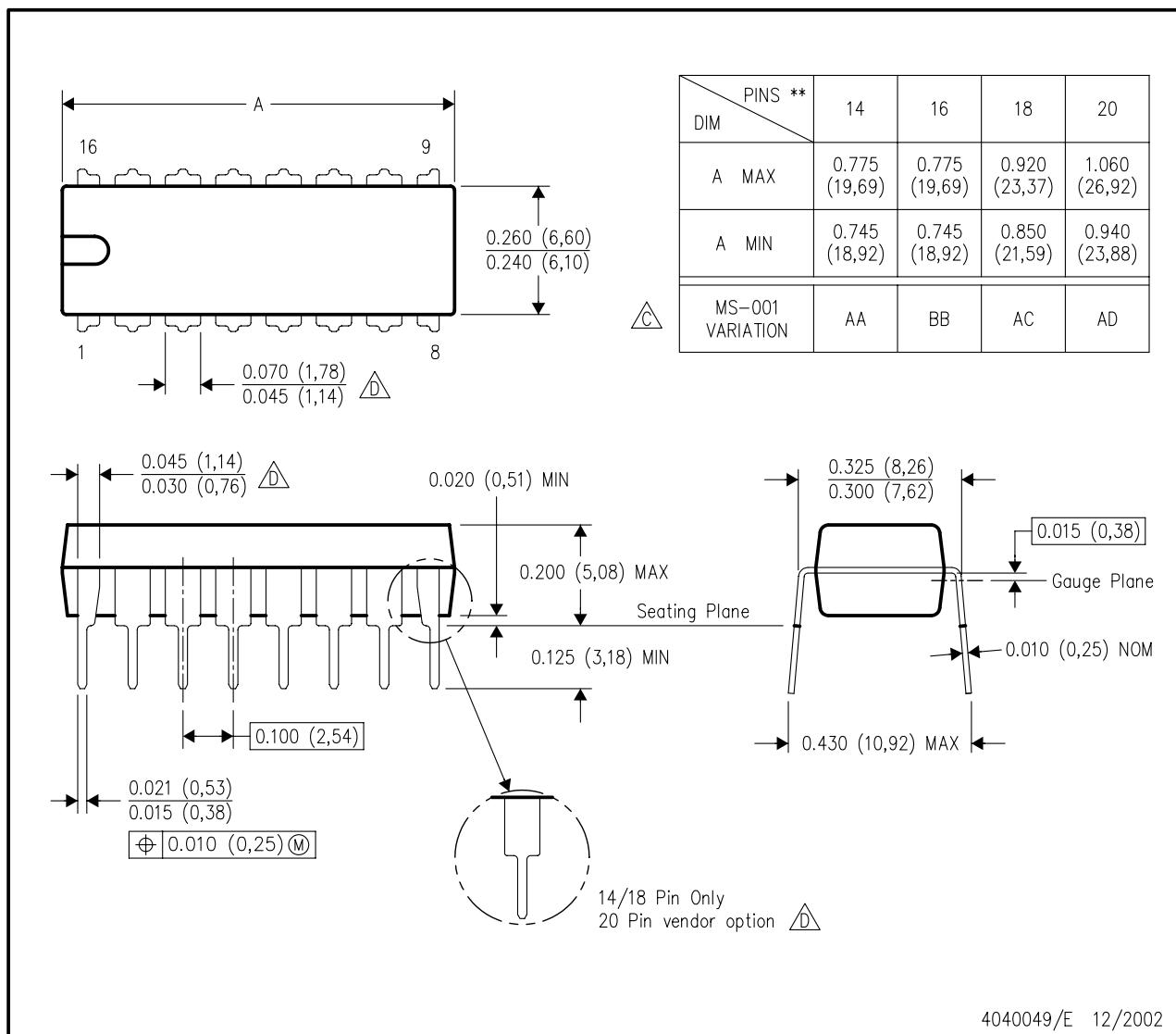
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ULN2004AIDR	SOIC	D	16	2500	333.2	345.9	28.6
ULN2004AINSR	SO	NS	16	2000	367.0	367.0	38.0

MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

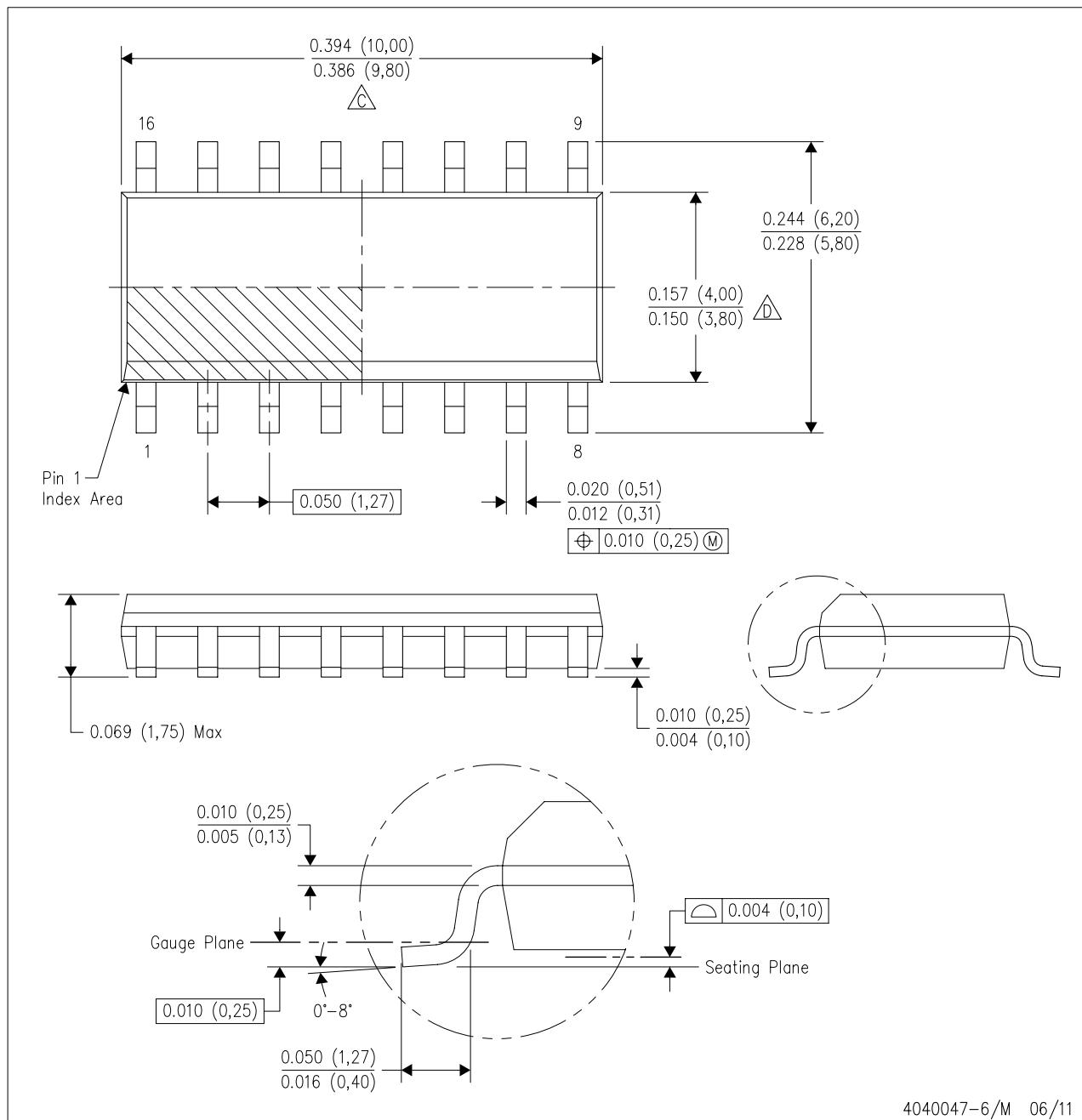
PLASTIC DUAL-IN-LINE PACKAGE



MECHANICAL DATA

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.

C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

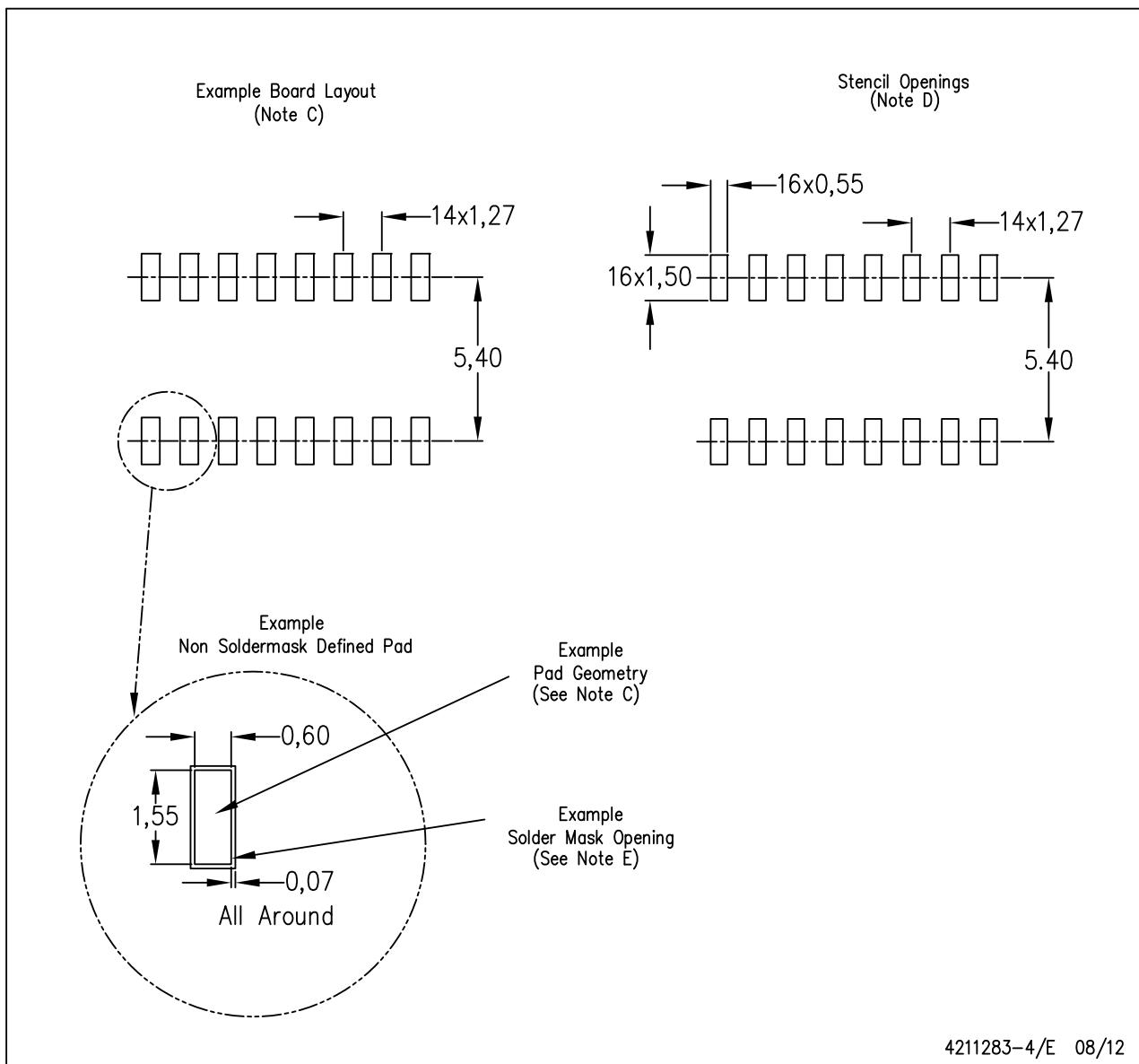
D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AC.

LAND PATTERN DATA

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

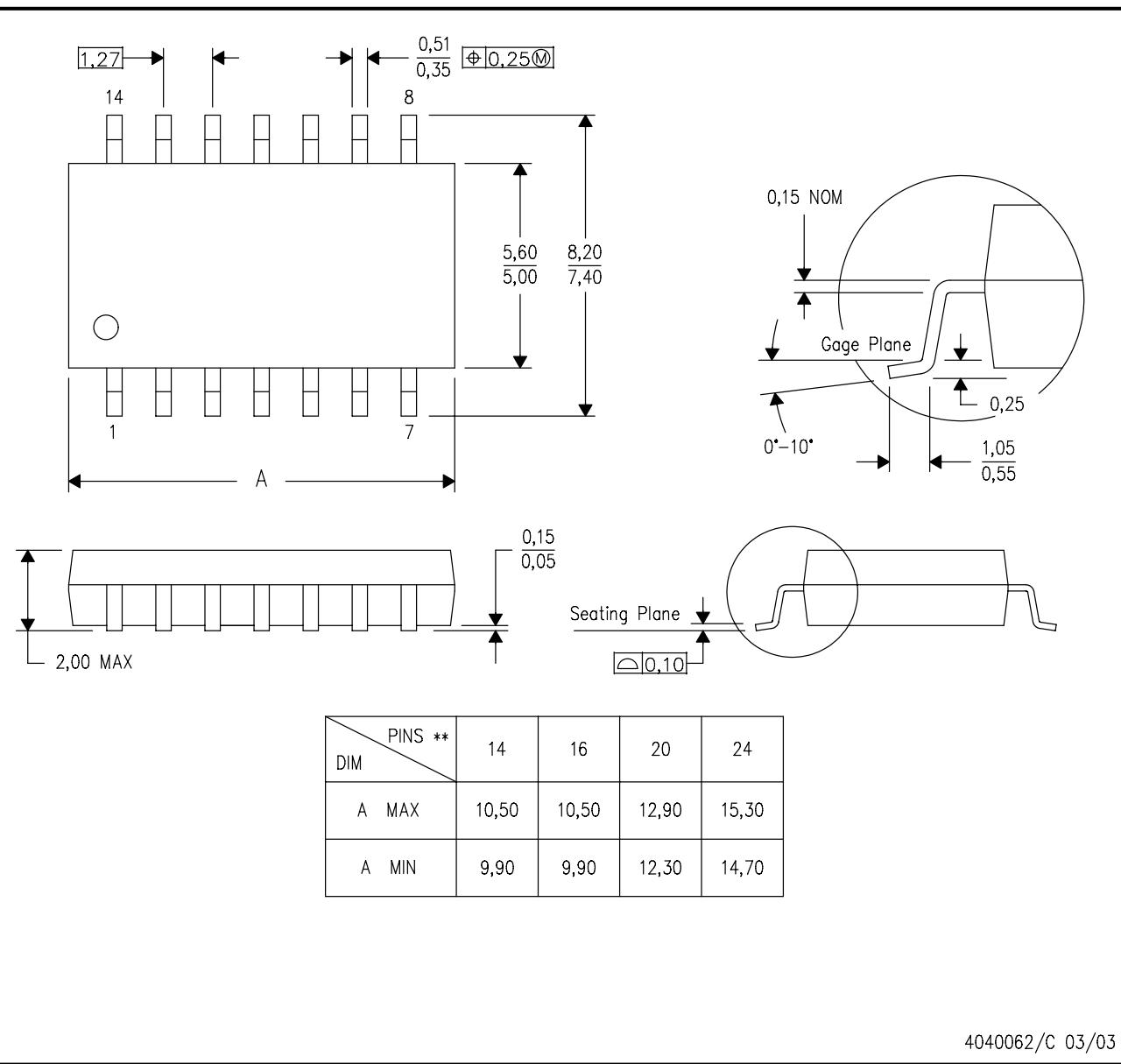
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity
	TI E2E Community
	e2e.ti.com